

ABOUT ICHSF 2027

The International Conference on High Speed Forming (ICHSF-2027) is a premier international forum dedicated to high-speed forming and high strain-rate manufacturing technologies. The conference brings together researchers, academicians, industry experts, and students from around the world to exchange ideas, present cutting-edge research, and discuss emerging developments in advanced manufacturing.

ICHSF-2027 welcomes original research contributions in electromagnetic forming, electrohydraulic forming, vaporizing foil actuator (VFA) processes, magnetic pulse welding, pulsed power systems, high-speed joining, and other advanced high-speed manufacturing processes.

ABOUT VJTI, MUMBAI

Established in 1887, Veermata Jijabai Technological Institute (VJTI), Mumbai, is one of India's oldest and most prestigious engineering institutions.

The Department of Production Engineering carries forward this legacy with a strong focus on advanced manufacturing, high strain-rate technologies, research, innovation, and industrial collaboration.

Hosting ICHSF-2027, VJTI opens its doors to the global research community in the vibrant city of Mumbai a perfect blend of tradition, technology, and transformation.



ICHSF 2027

INTERNATIONAL CONFERENCE ON HIGH SPEED FORMING 2027



8-9 March 2027

Organised by



Veermata Jijabai Technological Institute (VJTI Mumbai)

and

Indian Institute of Technology Goa (IIT Goa)

in partnership with



International Impulse Forming Group (I²FG)



Advancing Impulse-Based Manufacturing, Shaping the Future of High-Speed Forming

VENUE

VJTI, Mumbai, India

Mumbai, the financial capital of India, offers excellent connectivity, world-class infrastructure, industrial exposure, and a rich cultural heritage.

ATTRACTIONS AROUND MUMBAI



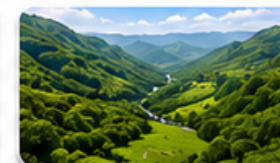
Gateway of India



Marine Drive



Elephanta Caves



Lonavala

CONFERENCE TOPICS



High-Speed Forming Technologies (Electromagnetic, Electrohydraulic, Explosive, VFA, Laser Shock, Impact Hydroforming)



High-Speed Joining, Welding & Solid-State Bonding



High-Speed Powder Compaction, Riveting, & Clinging Process



Failure, Fracture, Damage & Material Behaviour at High Strain Rates



Smart Manufacturing, AI, & Machine Learning in High-Speed Forming



Tool, Die & Process Design for High-Speed Forming



Advanced Diagnostics & In-situ Measurement Techniques in HSF.



Numerical Modeling, Multi-Physics Simulation & Digital Twins



Pulsed Power Systems & Energy Storage



Pulsed laser and energetic materials in high speed forming



IMPORTANT DATES



Abstract Submission Deadline
31 August 2026



Notification of Acceptance
30 September 2026



Full Paper Submission
30 November 2026



Revised Manuscript Submission
31 January 2027



Early Bird Registration Deadline
15 February 2027



Conference Dates
8-9 March 2027

SUBMIT ABSTRACT
using below link

[Click here to submit the Abstract](#)

REGISTRATION

Author Registration Includes:

- Access to all technical sessions
- Conference kit and refreshments
- Welcome reception
- Conference proceedings
- Certificate of participation
- Gala dinner last day

For more detail click on the link below:

<http://sponsership>

SPONSORING OPPORTUNITIES ARE OPENED



Dr. N Thirupathi

Conference Secretary

ichsf2027@evt.vjti.ac.in



<https://vjti.ac.in/>



+91 80995 01502

SCAN FOR WEBSITE



FOLLOW US

